OKI Semiconductor

This version: Aug. 1998

ML7000-01/02/03 ML7001-01/02/03

Single Rail CODEC

GENERAL DESCRIPTION

The ML7000/ML7001 are single-channel CMOS CODEC LSI devices for voice signals ranging from 300 to 3400 Hz with filters for A/D and D/A conversion.

Designed especially for a single-power supply and low-power applications, the devices are optimized for ISDN terminals, digital wireless systems, and digital PBXs.

The devices use the same transmission clocks as those used in the MSM7507.

With the differential analog signal outputs which can drive 60Ω load, the devices can directly drive a handset receiver.

FEATURES

• Single power supply: +5 V (ML7000-xx) +3 V (ML7001-xx)

Low power consumption

Operating mode: 25 mW Typ. $V_{DD} = 5.0 \text{ V (ML7000-xx)}$

20 mW Typ. $V_{DD} = 3.0 \text{ V (ML7001-xx)}$

Power-down mode: 0.05 mW Typ. $V_{DD} = 5.0 \text{ V (ML7000-xx)}$

0.03 mW Typ. $V_{DD} = 3.0 \text{ V (ML7001-xx)}$

• Conforms to ITU-T Companding law

ML7000-01/ML7001-01: μ /A-law pin selectable

ML7000-02/ML7001-02: μ-law ML7000-03/ML7001-03: A-law

- Transmission characteristics conform to ITU-T G.714
- Short frame sync timing operation
- Built-in PLL eliminates a master clock
- Serial data rate: 64/96/128/192/200/256/384/512/768/1024/1536/1544/2048 kHz
- Adjustable transmit gain
- Adjustable receive gain
- Built-in reference voltage supply
- Package options:

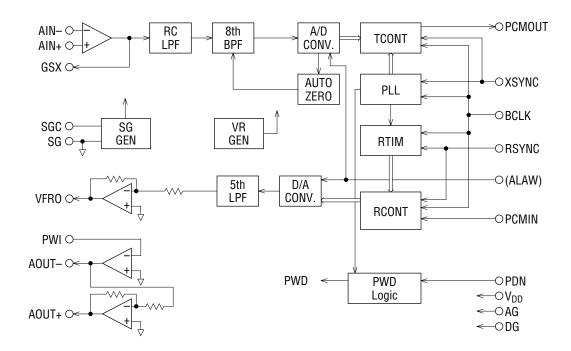
24-pin plastic SOP (SOP24-P-430-1.27-K) (Product name: ML7000-01MA/ML7001-01MA)

(Product name: ML7000-02MA/ML7001-02MA) (Product name: ML7000-03MA/ML7001-03MA)

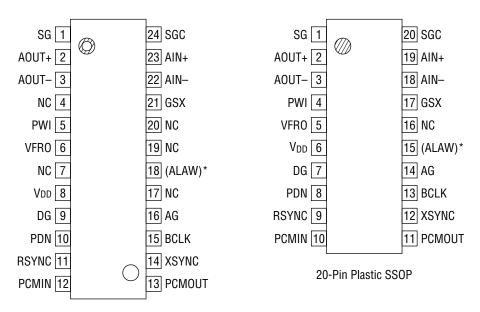
20-pin plastic SSOP (SSOP20-P-250-0.95-K) (Product name: ML7000-01MB/ML7001-01MB)

(Product name: ML7000-02MB/ML7001-02MB) (Product name: ML7000-03MB/ML7001-03MB)

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



24-Pin Plastic SOP

NC: No connect pin

^{*} The ALAW pin is only supported by the ML7000-01MA/ML7000-01MB/ML7001-01MA/ML7001-01MB.

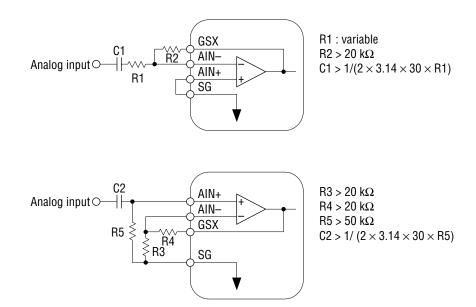
PIN FUNCTIONAL DESCRIPTION

AIN+, AIN-, GSX

Transmit analog input and transmit level adjustment.

AIN+ is a non-inverting input to the op-amp; AIN– is an inverting input to the op-amp; GSX is connected to the output of the op-amp.

The level adjustment should be performed using any of the methods shown below. During power-saving and power-down modes, the GSX output is at AG voltage.



AG

Analog ground.

VFRO

Receive filter output.

The output signal has an amplitude of 2.4 V_{PP} for ML7000-xx and 2.0 V_{PP} for ML7001-xx above and below the signal ground voltage (SG) when the digital signal of +3 dBm0 is input to PCMIN and can drive a load of 20 k Ω or more.

For driving a load of less than 20 k Ω , connect a resistor of 20 k Ω or more between the pins VFRO and PWI.

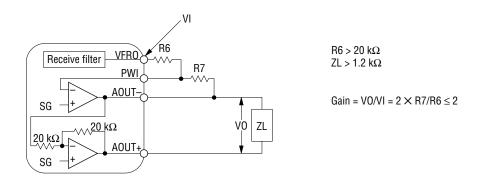
During power-saving or power-down mode, the VFRO output is at an SG level.

When adjusting the receive signal on the basis of frequency characteristics, refer to the Frequency Characteristics Adjustment Circuit.

PWI, AOUT+, AOUT-

PWI is connected to the inverting input of the receive driver.

The receive driver output is connected to the AOUT– pin. Therefore, the receive level can be adjusted with the pins VFRO, PWI, and AOUT–. During power-saving or power down-mode, the outputs of AOUT+ and AOUT– are in a high impedance state. The output of AOUT+ is inverted with respect to the output of AOUT–. Since these outputs provide differential drive of an impedance of 1.2 k Ω , they can directly be connected to a handset using a piezoelectric earphone or a line transformer. Refer to the application example.



V_{DD}

Power supply for +5 V (ML7000-xx) or +3 V (ML7001-xx)

PCMIN

PCM data input.

A serial PCM data input to this pin is converted to an analog signal in synchronization with the RSYNC signal and BCLK signal.

The data rate of PCM is equal to the frequency of the BCLK signal.

PCM signal is shifted in at the falling edge of the BCLK signal and latched into the internal register when shifted by eight bits.

The start of the PCM data (MSD) is identified at the rising edge of RSYNC.

BCLK

Shift clock signal input for the PCMIN and PCMOUT signals.

The frequency, equal to the data rate, is 64, 96, 128, 192, 256, 384, 512, 768, 1024, 1536, 1544, or 2048 kHz. Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

RSYNC

Receive synchronizing signal input.

Eight required bits are selected from serial PCM signals on the PCMIN pin by the receive synchronizing signal.

Signals in the receive section are synchronized by this synchronizing signal. This signal must be synchronized in phase with the BCLK. The frequency should be $8\,\mathrm{kHz}\pm50\,\mathrm{ppm}$ to guarantee the AC characteristics which are mainly the frequency characteristics of the receive section.

However, if the frequency characteristic of an applied system is not specified exactly, this device can operate in the range of 6 to 9 kHz, but the electrical characteristics in this specification are not guaranteed.

XSYNC

Transmit synchronizing signal input.

The PCM output signal from the PCMOUT pin is output in synchronization with this signal. This synchronizing signal triggers the PLL and synchronizes all timing signals of the transmit section. This synchronizing signal must be synchronized in phase with BCLK.

The frequency should be $8 \text{ kHz} \pm 50 \text{ ppm}$ to guarantee the AC characteristics which are mainly the frequency characteristics of the transmit section. However, if the frequency characteristic of an applied system is not specified exactly, this device operates in the range of 6 to 9 kHz, but the electrical characteristics in this specification are not guaranteed.

Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

DG

Ground for the digital signal circuits.

This ground is separate from the analog signal ground AG. The DG pin must be connected to the AG pin on the printed circuit board to make a common analog ground AG.

PDN

Power down control signal.

A logic "0" level drives both transmit and receive circuits to a power down state.

PCMOUT

PCM signal output.

Synchronizing with the rising edge of the BCLK signal, the PCM output signal is output from MSD in a sequential order.

MSD may be output at the rising edge of the XSYNC signal, based on the timing between BCLK and XSYNC.

This pin is in a high impedance state except during 8-bit PCM output. It is also in a high impedance state during power saving or power down mode.

A pull-up resistor must be connected to this pin because its output is configured as an open drain. This device is compatible with the ITU-T recommendation on coding law and output coding format.

The ML7000-03 (A-law) and ML7001-03 (A-law) output the character signal, inverting the even bits.

		PCMIN/PCMOUT														
Input/Output Level		ML7000-02 (μ-law)					ML7000-03 (A-law) ML7001-03 (A-law)									
		ML7001-02 (μ-law)														
+Full scale	MSD							LSD	MSD							LSD
+Full Scale	1	0	0	0	0	0	0	0	1	0	1	0	1	0	1	0
+0	1	1	1	1	1	1	1	1	1	1	0	1	0	1	0	1
-0	0	1	1	1	1	1	1	1	0	1	0	1	0	1	0	1
–Full scale	0	0	0	0	0	0	0	0	0	0	1	0	1	0	1	0

SG

Signal ground voltage output.

The output voltage is 1/2 of the power supply voltage.

The output drive current capability is ±300 µA for ML7000-xx and ±200 µA for ML7001-xx.

This pin provides the SG level for CODEC peripherals.

This output voltage level is undefined during power-saving or power-down mode.

SGC

Used to generate the signal ground voltage level by connecting a bypass capacitor. Connect a $0.1\,\mu F$ capacitor with excellent high frequency characteristics between the AG pin and the SGC pin.

ALAW

Control signal input of the companding law selection.

Only the ML7000-01MA/ML7000-01MB/ML7001-01MA/ML7001-01MB have this pin. The CODEC will operate in the μ -law when this pin is at a logic "0" level and the CODEC will operate in the A-law when this pin is at a logic "1" level. The CODEC operates in the μ -law if the pin is left open, since the pin is internally pulled down.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V _{DD}	_	-0.3 to +7	V
Analog Input Voltage	V _{AIN}	_	-0.3 to V _{DD} + 0.3	V
Digital Input Voltage	V _{DIN}	_	-0.3 to V _{DD} + 0.3	V

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	
Power Supply Voltage	V _{DD}		4.75	5.00	5.25	V	
	V DD	_	2.70	3.00	3.30	V	
Operating Temperature	Ta	_	-30	+25	+85	°C	
Analog Input Voltage	\ \/	Connect AIN– and GSX			2.4	V_{PP}	
Allalog iliput voltage	V _{AIN}	Connect Ann— and GOA	_	_	1.2	V PP	
High Level Input Voltage	V _{IH}		2.2		V_{DD}	V	
	VIH	XSYNC, RSYNC, BCLK,	0.45×V _{DD}		V_{DD}	v	
Low Level Input Voltage	V _{IL}	PCMIN, PDN, ALAW	0		0.8	V	
Low Level input voltage	V IL		0	_	$0.16 \times V_{DD}$	V	
			64, 96, 12	28, 192, 20	00, 256,		
Clock Frequency	F _C	BCLK	384, 512,	l, 1536,	kHz		
			1544, 204	18			
Sync Pulse Frequency	F _S	 XSYNC, RSYNC (-40 to +75 °C)	6.0	8.0	9.0	kHz	
Sync ruise rrequency	18	73 TNO, N3 TNO (-40 to +73 °C)	6.0	8.0	10.0	KI IZ	
Clock Duty Ratio	D _C	BCLK	40	50	60	%	
Digital Input Rise Time	t _{lr}	XSYNC, RSYNC, BCLK,	_	_	50	ns	
Digital Input Fall Time	t _{lf}	PCMIN, PDN	_	_	50	ns	
Transmit Sync Pulse Setting Time	t _{CX}	BCLK→XSYNC, See Fig. 1	50		_	ns	
	t _{XC}	XSYNC→BCLK, See Fig. 1	50	_	_	ns	
XSYNC Setup Time	t _{XS}	_	50	_	_	ns	
XSYNC Hold Time	t _{XH}	_	50	_	_	ns	
Receive Sync Pulse Setting Time	t _{CR}	BCLK→RSYNC, See Fig. 1	50		_	ns	
Theceive Sylic I uise Setting Time	t _{RC}	RSYNC→BCLK, See Fig. 1	50		_	ns	
RSYNC Setup Time	t _{RS}	_	50	_	_	ns	
RSYNC Hold Time	t _{RH}	_	50	_	_	ns	
PCMIN Setup Time	t _{DS}	_	50	_	_	ns	
PCMIN Hold Time	t _{DH}	_	50	_	_	ns	
Digital Output Load	R _{DL}	Pull-up resistor	0.5	_	_	kΩ	
Digital Output Loau	C _{DL}	_	_	_	100	pF	
Analog Input Allowable DC Offeet	V	Transmit gain stage, Gain = 0 dB	-10	_	+10	mV	
Analog Input Allowable DC Offset	V _{off}	Transmit gain stage, Gain = +20 dB	-100		+100	mV	
Allowable Jitter Width	-	XSYNC, RSYNC, BCLK	_		1000	ns	

ELECTRICAL CHARACTERISTICS

DC and Digital Interface Characteristics

(ML7001-xx: V_{DD} = 2.7 V to 3.3 V, Ta = -30 to +85°C) (ML7000-xx: V_{DD} = +5.0 V ±5%, Ta = -30 to +85°C)

Parameter	Symbol	Condit	Min.	Тур.	Max.	Unit	
	1	Operating mode	$V_{DD} = 5.0 \text{ V}$		5.0	12.0	mΛ
	I _{DD1}	No signal	_	6.5	10.0	mA	
Power Supply Current		Power-saving mo	ode, PDN = 1,		1.5	4.0	mA
	I _{DD2}	$XSYNC \rightarrow OFF$			2.0	8.0	IIIA
	,	Power-down mod	de, PDN = 0,		0.01	0.05	m 1
	I _{DD3}	BCLK OFF	_	0.01	0.05	mA	
High Level Input Voltage	V _{IH}		2.2	<u> </u>	V_{DD}	V	
		_	$0.45 \times V_{DD}$	_	V_{DD}	V	
Low Lovel Input Voltage	W		0.0		0.8	V	
Low Level Input Voltage	V _{IL}	_	0.0	-	$0.16 \times V_{DD}$		
High Level Input Leakage Current	I _{IH}	_		_	_	2.0	μΑ
High Level Input Leakage Current	I _{IH2}	ALAW		_		30.0	μΑ
Low Level Input Leakage Current	I _{IL}	_	_			0.5	μΑ
Digital Output Low Voltage	V _{OL}	Pull-up resistor =	0.0	0.2	0.4	V	
Digital Output Leakage Current	I ₀	_	_	_	10	μΑ	
Input Capacitance	CIN	_		_	5	_	pF

Transmit Analog Interface Characteristics

(ML7001-xx: $V_{DD} = 2.7 \text{ V to } 3.3 \text{ V}$, $Ta = -30 \text{ to } +85^{\circ}\text{C}$) (ML7000-xx: $V_{DD} = +5.0 \text{ V } \pm 5\%$, $Ta = -30 \text{ to } +85^{\circ}\text{C}$)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input Resistance	R _{INX}	AIN+, AIN-	10	_	_	MΩ
Output Load Resistance	R _{LGX}	GSX with respect to SG	20	_	_	kΩ
Output Load Capacitance	C _{LGX}		_	_	30	pF
Output Amplitude	V		-1.2	_	+1.2	VOn
Output Amplitude	V _{OGX}		-0.7	_	+0.7	V0p
Offset Voltage	Vosgx	Gain = 1	-20		+20	mV

Values above the dotted line are for ML7000-xx; those below, for ML7001-xx.

Receive Analog Interface Characteristics

(ML7001-xx: V_{DD} = 2.7 V to 3.3 V, Ta = -30 to +85°C) (ML7000-xx: V_{DD} = +5.0 V ±5%, Ta = -30 to +85°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	
Input Resistance	R _{INPW}	PWI	10	_	_	MΩ	
	R _{LVF}	VFRO with respect to SG	20	_	_	kΩ	
Output Load Resistance	D	AOUT+, AOUT- (each) with	0.6			10	
	R _{LAO}	respect to SG	0.6	_	_	kΩ	
Output Load Capacitance	C _{LVF} VFRO		_	_	30	pF	
	C _{LAO}	AOUT+, AOUT-	_	_	50	pF	
	W	VFR0, $R_L = 20 \text{ k}\Omega$ with	-1.2	_	+1.2		
Outnut Amplitudo	V _{OVF}	respect to SG	-1.0		+1.0	Von	
Output Amplitude		AOUT+, AOUT-, $R_L = 0.6 \text{ k}\Omega$	-1.3	_	+1.3	V0p	
	V _{OAO}	with respect to SG	with respect to SG -1.0 -		+1.0		
Offset Voltage	V _{OSVF}	VFRO with respect to SG	-100	_	+100	mV	
	V	AOUT+, AOUT-, Gain = 1 with	100		.100	m\/	
	V _{OSAO}	respect to SG	-100	_	+100	mV	

AC Characteristics

(ML7001-xx: $F_S = 8$ kHz, $V_{DD} = 2.7$ V to 3.3 V, Ta = -30 to +85°C) (ML7000-xx: $F_S = 8$ kHz, $V_{DD} = +5.0$ V ± 5 %, Ta = -30 to +85°C)

	(IVIL/000-XX. F			7	V _{UU} = 10.	0 V ±0 /0, I	u = 00 to	100 0)
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	Loss T1	60			20	26		-
	Loss T2	300			-0.15	+0.07	+0.2	
Transmit Fraguency Decrease	Loss T3	1020				Reference		40
Transmit Frequency Response	Loss T4	2020	0		-0.15	-0.04	+0.2	dB
	Loss T5	3000			-0.15	+0.07	+0.2	
	Loss T6	3400			0	0.4	0.8	
	Loss R1	300			-0.15	-0.03	+0.2	
	Loss R2	1020				Reference		
Receive Frequency Response	Loss R3		0		-0.15	0.00	+0.2	dB
	Loss R4	3000			-0.15	+0.05	+0.2	
	Loss R5	3400			0	0.54	0.8	
	SD T1		3		35	43	_	
Transmit Signal to Distortion Ratio	SD T2		0		35	41	_	
	0D T0		00		35.0	38.0	_	dB
	SD T3	1000	-30		34.0	38.0		
	SD T4	1020	-40	*1	26.0	31.0	_	
					26.0	30.0		
	SD T5		-45		24.0	25.0	_	
					—	25.0		
	SD R1		3		36	43	_	
	SD R2		0		36	41	_	dB
					36.0	40.0	_	
B : 0: 11 B: 1 !: B !!	SD R3	4000	-30		35.0	40.0		
Receive Signal to Distortion Ratio	00.04	1020	40	*1	25.0	32.0	_	
	SD R4		-40		26.0	32.0		1
	00.05		4.5		25.0	27.0	_	1
	SD R5		-45		—	27.0		
	GT T1		3		-0.3	+0.01	+0.3	
	GT T2		-10			Reference		
Transmit Gain Tracking	GT T3	1020	-40		-0.3	-0.05	+0.3	dB
g	GT T4		-50		-0.6	-0.05	+0.6	
	GT T5		-55]	-1.2	-0.08	+1.2	1
	GT R1		3		-0.3	-0.06	+0.3	
	GT R2		-10]		Reference	1	1
Receive Gain Tracking	GT R3	1020	-40		-0.3	+0.08	+0.3	dB
,	GT R4		-50]	-0.6	+0.12	+0.6	1
	GT R5		-55		-1.2	+0.15	+1.2	1

^{*1} Psophometric filter is used.

AC Characteristics (Continued)

(ML7001-xx: $F_S = 8$ kHz, $V_{DD} = 2.7$ V to 3.3 V, Ta = -30 to +85°C) (ML7000-xx: $F_S = 8$ kHz, $V_{DD} = +5.0$ V $\pm 5\%$, Ta = -30 to +85°C)

		(-, 000 , , , ,	. 0,	- 00	, .		,
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	NC-U- T	, ,		AIN = SG	_	-73.0	-66.0	
Idla Olasasal Naisa	Nidle T	_	_	*1 *2	<u> </u>	-69.5	-65.0	1
Idle Channel Noise	Ni dia D			*1 *2	_	-78.0	-71.0	dBm0p
	Nidle R	_	_ _	1 "2	—	-75.0	-65.0	1
	A)/ T			$V_{DD} = 5.0 \text{ V},$ $Ta = 25^{\circ}\text{C}$	0.58	0.6007	0.622	
	AV T	1020	0	V _{DD} = 3.0 V, Ta = 25°C	0.338	0.35	0.362	Vrms
Absolute Level (Initial Difference)	A) / D			*0	0.58	0.6007	0.622	1
	AV R			*3	0.483	0.5	0.518	1
Absolute Level	AV Tt	V _{DD} = 5 V ±5	5%, Ta = -30	to 85°C *3	-0.2	_	0.2	٩D
(Deviation of Temperature and Power)	AV Rt	$V_{DD} = 2.7 \text{ to}$	3.3 V, Ta = −3	30 to 85°C *3	-0.2	_	0.2	dB
Absolute Delay	Td	1020	0	A to A BCLK = 64 kHz	_	_	0.6	ms
	t _{GD} T1	500			_	0.19	0.75	
	t _{GD} T2	600			_	0.11	0.35	1
Transmit Group Delay	t _{GD} T3	1000	0	*4	_	0.02	0.125	ms
	t _{GD} T4	2600			_	0.05	0.125	
	t _{GD} T5	2800			_	0.07	0.75	
	t _{GD} R1	500			_	0.00	0.75	
Receive Group Delay	t _{GD} R2	600			_	0.00	0.35	ms
	t _{GD} R3	1000	0	*4	_	0.00	0.125	
	t _{GD} R4	2600			_	0.09	0.125	
	t _{GD} R5	2800			_	0.12	0.75	
Crosstalk Attanuation	CR T	1020	0	$TRANS \to RECV$	_	-85	-75	dB
Crosstalk Attenuation	CR R	1020	0	$RECV \to TRANS$	_	-76	-70	ub

^{*1} Psophometric filter is used.

^{*2} Input "0" code to PCMIN.

^{*3} AVR is defined at VFRO output.

^{*4} With respect to minimum value of the group delay distortion.

AC Characteristics (Continued)

 $\begin{array}{ll} (ML7001\text{-}xx: \;\; F_S=8 \; kHz, \; V_{DD}=2.7 \; V \; to \; 3.3 \; V, \; Ta=-30 \; to \; +85 °C) \\ (ML7000\text{-}xx: \;\; F_S=8 \; kHz, \; V_{DD}=+5.0 \; V \; \pm5\%, \; Ta=-30 \; to \; +85 °C) \end{array}$

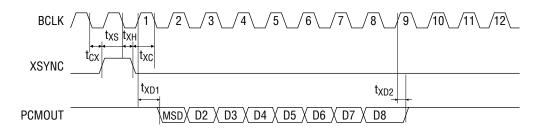
				<u> </u>				
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
Discrimination	DIS	4.6 kHz to	0	0 to	30	32	_	dB
		72 kHz		4000 Hz				
Out-of-band Spurious	S	300 to	0	4.6 kHz to		-37.5	-35	dBm0
	J	3400		100 kHz	_			ubilio
Intermodulation Distortion	IMD	fa = 470	-4	2fa – fb	_	-52	-35	dBm0
intermodulation distortion	IIVID	fd = 320						ubilio
Dowar Cupply Noise Dejection Datio	PSR T	0 to	50 mVpp	Measured		30	_	dB
Power Supply Noise Rejection Ratio	PSR R	50 kHz	OU IIIVPP	inband *5				ub
Digital Output Delay Time	t _{XD1}	C _L = 100 p	F + 1 LST	TL	20	_	200	200
	t _{XD2}	Pull-up re	sistor = 50	Ω 0	20	_	200	ns

^{*5} Measured under idle channel noise.

TIMING DIAGRAM

PCM Data Input/Output Timing

Transmit Timing



Receive Timing

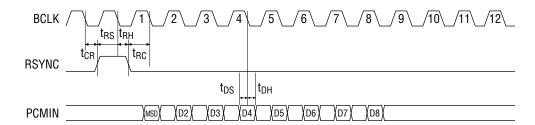
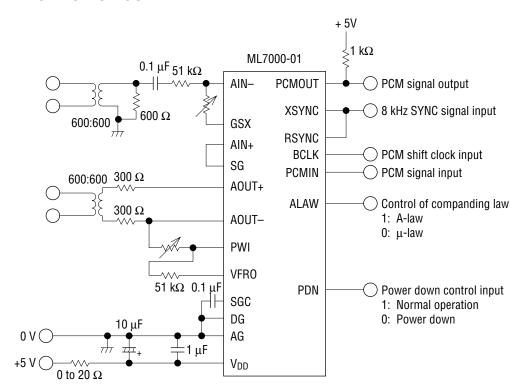
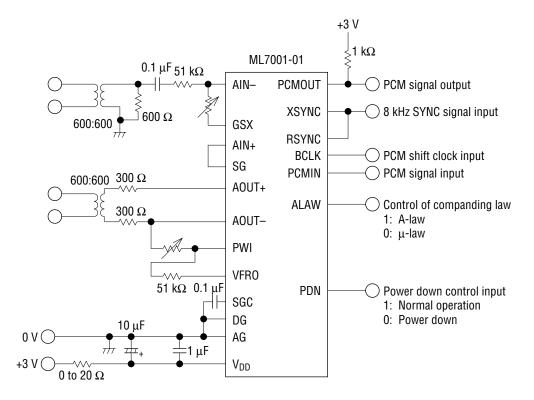


Figure 1 Basic Timing

APPLICATION CIRCUIT



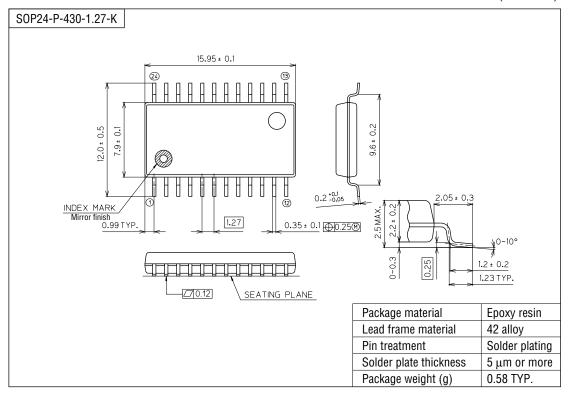


NOTES ON USE

- To ensure proper electrical characteristics, use bypass capacitors with excellent high frequency characteristics for the power supply and keep them as close as possible to the device pins.
- Connect the AG pin and the DG pin as closely as possible. Connect to the system ground with low impedance.
- Mount the device directly on the board when mounted on PCBs. Do not use IC sockets. If the use of IC socket is unavoidable, use the short lead type socket.
- When mounted on a frame, use electromagnetic shielding if any electromagnetic wave sources such as power supply transformers surrounds the device.
- Keep the voltage on the V_{DD} pin not lower than -0.3 V even instantaneously to avoid latchup that may otherwise occur when power is turned on.
- Use a low noise (particularly, low level type of high frequency spike noise or pulse noise) power supply to avoid erroneous operation and the degradation of the characteristics of these devices.

PACKAGE DIMENSIONS

(Unit: mm)

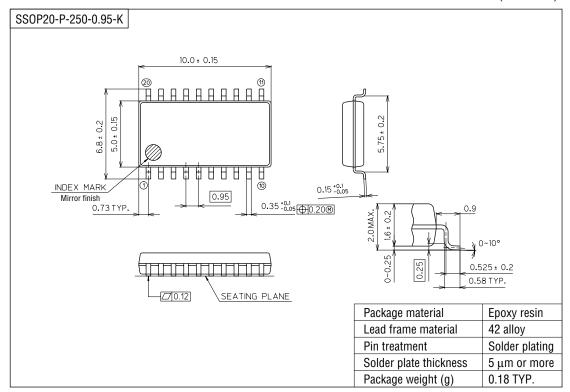


Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, SOJ, QFJ (PLCC), SHP and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

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